

Description

The Gas Discharge Tube (GDT) is a protective device which is filled with certain proportion of noble gas, or mixed gas or other discharge media in the space between metal electrodes and metalized ceramics, and then sealed at high temperature to form a single-gap or multi-gap switch type protective device. When the protected circuit or equipment suffers to surge, GDT will change from high impedance state to low impedance state and release the surge energy to reduce the residual voltage of the circuit, and then protect the equipment or humanbody from the hazard of transient overvoltage.

Features

- Fast Response
- Stable Performance Over Surface Life
- High Current Rating
- Low Capacitance
- High Insulation Resistance
- RoHS & REACH Compliant

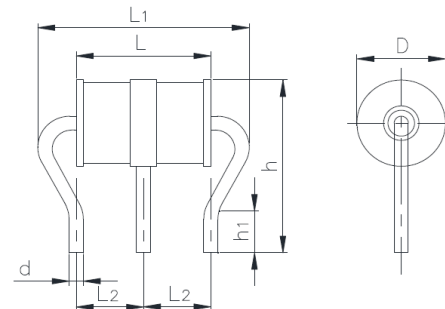
Applications

- WLAN xDSL
- CATV
- MDF
- Ethernet
- BTS(Base Station)
- Power Supply
- Antenna and RF
- Consumer Electronics
- N-PE Protection in AC Power

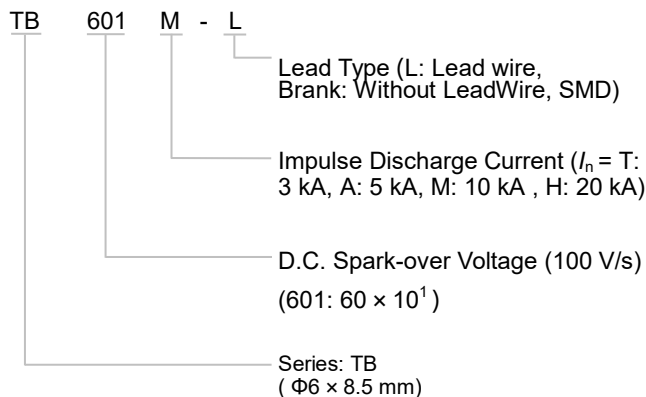
Agency Approvals

Agency	Standards	File No.
	UL497B	on request
	TUV	On-going

Dimensions (mm)



Part Number System



D	h	L	d
$\Phi 6.0 \pm 0.2$	10.0 ± 1.0	8.5 ± 0.2	$\Phi 0.8 \pm 0.1$
h1	L1	L2	
2.5	12.0 Max	4.4 ± 0.3	

Glossary

Item	Description
V_s	D.C. Spark-over Voltage The voltage at which the GDT sparks over with slowly increasing d.c. voltage. — (IEC 61643-311)
V	Impulse Spark-over Voltage The highest Voltage which appears across the terminals of a GDT in the period between the application of an impulse of given wave-shape and the time when current begins to flow. — (ITU-T K.12)
V_a	Arc Voltage Voltage drop across the GDT during arc current flow. — (IEC 61643-311)
V_{gl}	Glow Voltage The peak value of the voltage drop across the GDT when a glow-current is flowing. It is sometimes called the glow mode voltage. — (ITU-T K.12)
8/20 μ s	8/20 Current Impulse Current impulse with a nominal virtual front time of 8 μ s and a nominal time to half-value of 20 μ s. — (IEC 61643-11)
1.2/50 μ s	1.2/50 Voltage Impulse Voltage impulse with a nominal virtual front time of 1.2 μ s and a nominal time to half-value of 50 μ s. — (IEC 61643-11)
I	Alternating Discharge Current The r.m.s. value of an approximately sinusoidal alternating current passing through the GDT. — (ITU-T K.12)
I_n	Nominal Discharge Current Crest value of the current through the GDT having a current waveshape of 8/20 μ s. — (IEC 61643-11)
I_{max}	Maximum Discharge Current Crest value of a current through the GDT having an 8/20 μ s waveshape and magnitude according to the manufacturers specification. I_{max} is equal to or greater than I_n . — (IEC 61643-11)

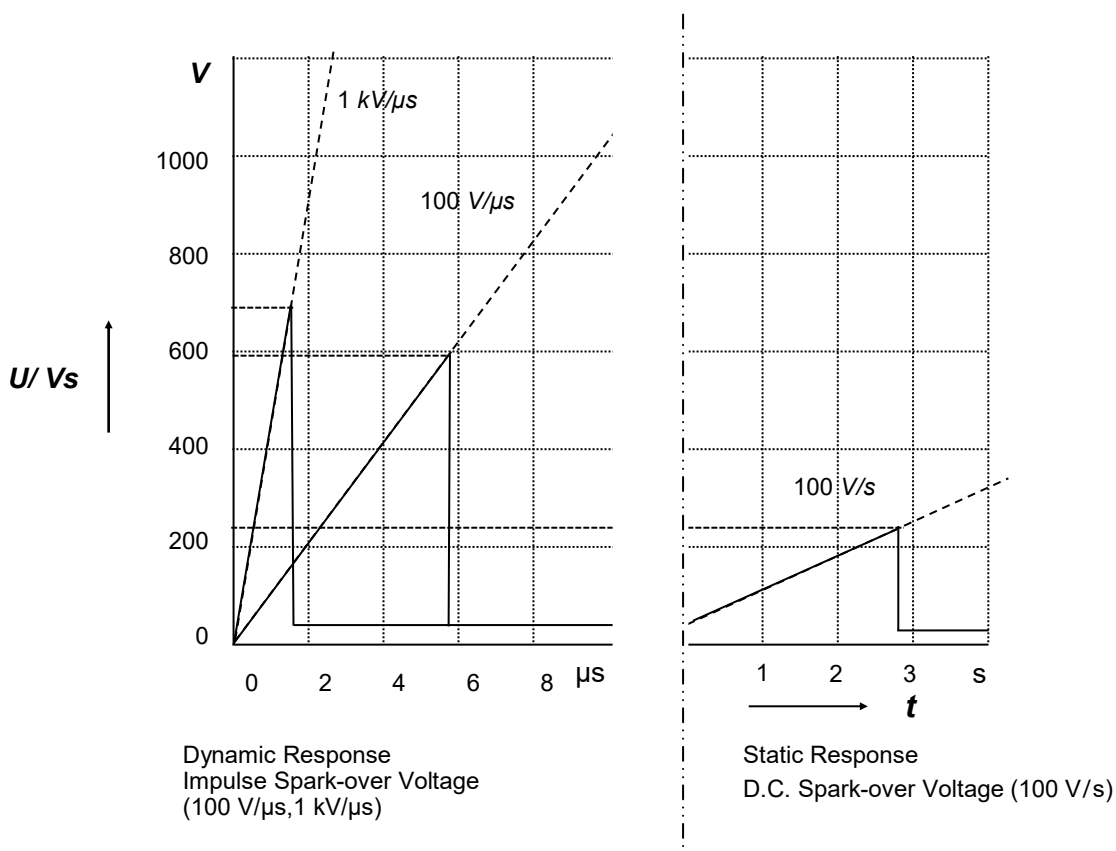
Specifications

Model	D.C. Spark-over Voltage @100 V/s	Tolerance of V_s	Impulse Spark-over Voltage @1 kV/μs	Arc Voltage @1 A	Impulse Discharge Current @8/20 μs	Alternating Discharge Current @50Hz 1 s	Insulation Resistance		Capacitance 0.5 VDC @ 1MHz	Agency Approvals		
	V_s	V_s	V	V_a	I_n	I	V_{DC}	IR	C			
	V	V	V	A	kA	A (r.m.s.)	V	GΩ	(pF)	UL497B	UL1449	TUV
TB091A - L	90	72 ~ 108	≤ 600	≈ 8	5	5	50	≥ 1	≤ 1.0	●	N/A	○
TB151A - L	150	120 ~ 180	≤ 600	≈ 8	5	5	50	≥ 1	≤ 1.0	●	N/A	○
TB231A - L	230	184 ~ 280	≤ 700	≈ 10	5	5	100	≥ 1	≤ 1.0	●	N/A	○
TB351A - L	350	280 ~ 420	≤ 1000	≈ 10	5	5	100	≥ 1	≤ 1.0	●	N/A	○
TB421A - L	420	336 ~ 504	≤ 1000	≈ 12	5	5	100	≥ 1	≤ 1.0	○	N/A	○
TB471A - L	470	376 ~ 564	≤ 1200	≈ 12	5	5	100	≥ 1	≤ 1.0	○	N/A	○
TB601A - L	600	480 ~ 720	≤ 1400	≈ 15	5	5	100	≥ 1	≤ 1.0	○	N/A	○
TB091M - L	90	72 ~ 108	≤ 600	≈ 8	10	10	50	≥ 1	≤ 1.0	●	N/A	○
TB151M - L	150	120 ~ 80	≤ 600	≈ 8	10	10	50	≥ 1	≤ 1.0	●	N/A	○
TB231M - L	230	184 ~ 280	≤ 700	≈ 10	10	10	100	≥ 1	≤ 1.0	●	N/A	○
TB351M - L	350	280 ~ 420	≤ 1000	≈ 10	10	10	100	≥ 1	≤ 1.0	●	N/A	○
TB421M - L	420	336 ~ 504	≤ 1000	≈ 12	10	10	100	≥ 1	≤ 1.0	○	N/A	○
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TB601M - L	600	480 ~ 720	≤ 1400	≈ 15	10	10	100	≥ 1	≤ 1.0	○	N/A	○

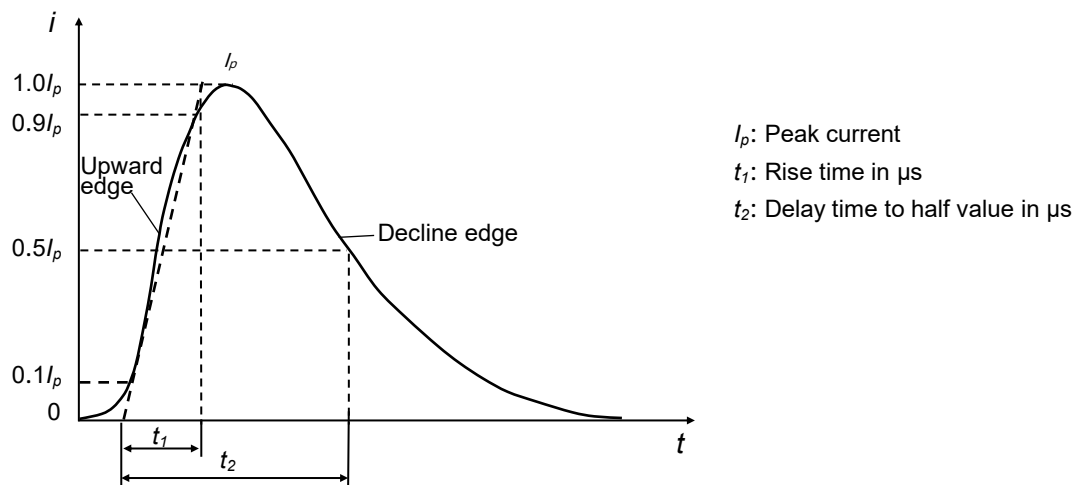
Note:

1. The above parameters based on ITU - T K12 & IEC61643.311 standards.
2. "●" means GDT has gained the certification.
"○" means GDT is planned to apply for certification.
3. "*" Means different wire type, such as "SMD" means SMD shape, "L" means lead wire.
4. Impulse discharge current value refers to the current value of simultaneous discharge of both ends to the ground.

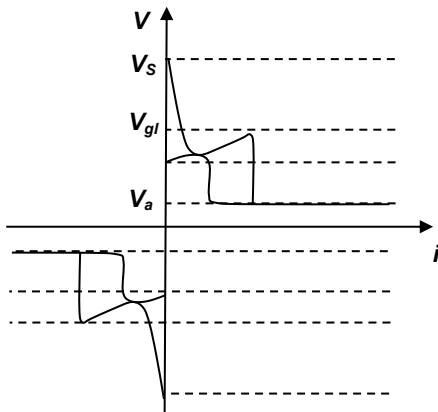
Reference Curve for Spark-over Voltage (Refer to 230 VDC)



Reference Curve for Impulse Discharge Current

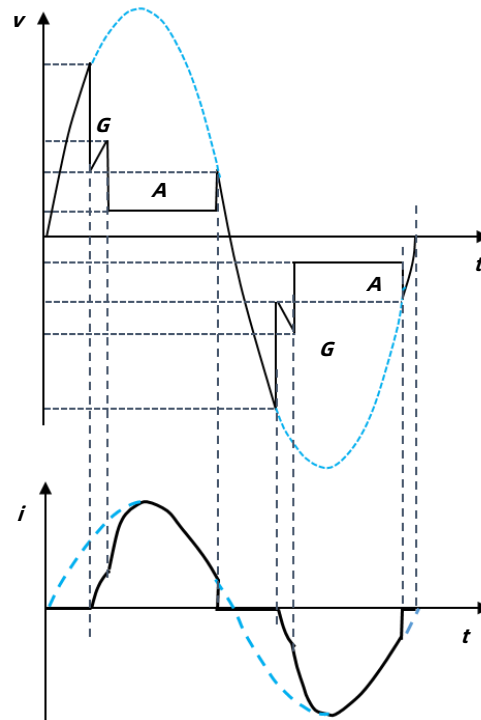


Electrical Characteristics



Relationship between Current and Voltage

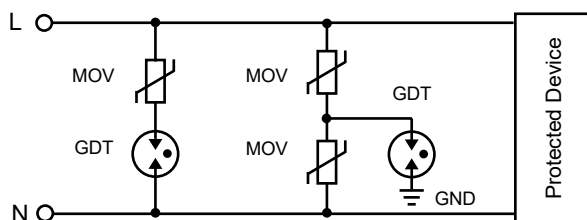
V_s : Spark-over Voltage
 V_{gl} : Glow Voltage
 V_a : Arc Voltage
 G : Glow Mode
 A : Arc Mode



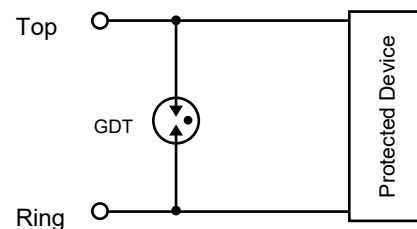
Time Variation Patterns of Voltage and Current

Application Example

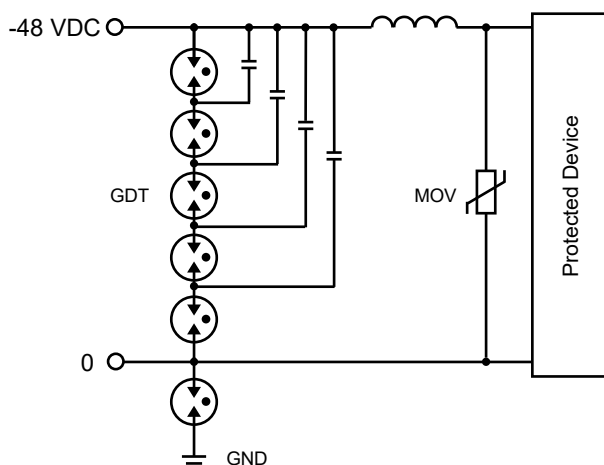
AC Power Protection



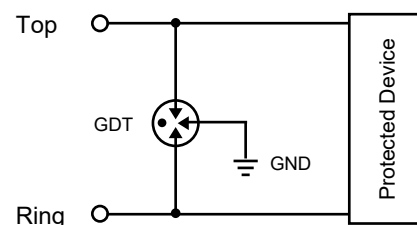
2-Electrod GDT Signal Circuit Protection



DC Power Protection



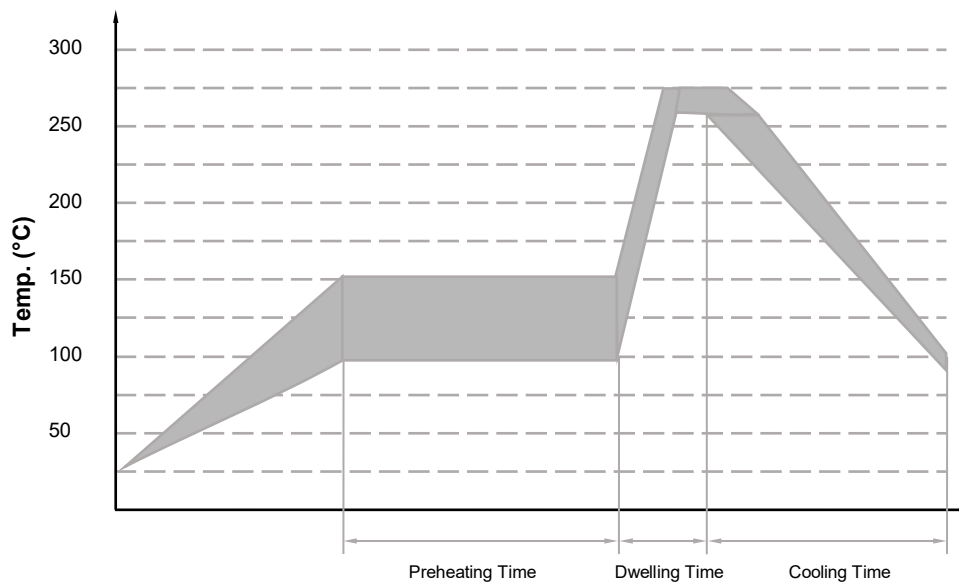
3-Electrod GDT Signal Circuit Protection



Recommended Hand-soldering Parameters

Items	Condition
Soldering Iron Temperature	350 °C (Max.)
Soldering Time	4 s (Max.)
Space between soldering point and product body	2 mm (Min.)

Wave Soldering Parameters (For Reference Only)

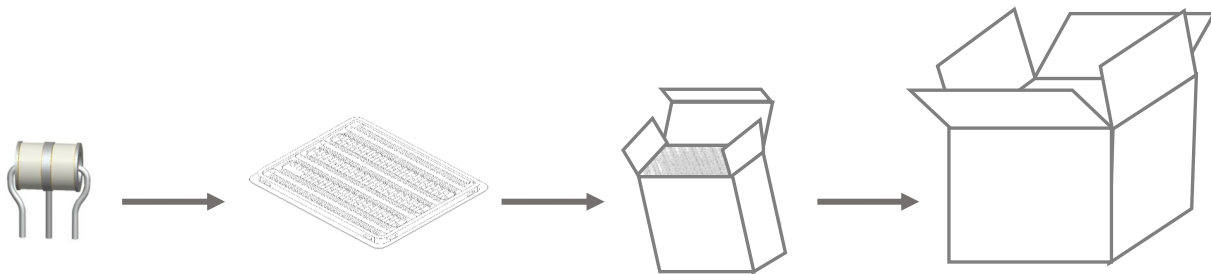


Item	Temp. (°C)	Time (s)
Preheating	90 to 150	< 150
Dwelling	255 to 280	3 to 10

Packaging Information

1. PC Box Package (Leaded Type Shaped Lead Devices)

Item	Reel	Inner Box	Carton
Dimensions (mm)	215 × 205 × 12.5	230 × 210 × 60	480 × 230 × 320
Quantity (PCS)	100	500	5000
Notes: Packaging dimensions and quantity are for reference only.			



Please refer to the specifications for the packaging details.



ATTENTION

Usage

1. Do not operate GDT in power supply networks, whose maximum operation voltage exceeds the minimum spark-overvoltage of the GDT.
2. The GDT may become hot in the event of longer periods of current stress (burn risk). In the event of overload the connectors may fail or the component may be destroyed.
3. If the contacts of GDT are defective, current load can cause sparks and loud noises.
4. When air pressure is from 55 kPa to 106 kPa. The relative altitude shall be +5000 m to –500 m.

Replacement

The GDT is a non-repairable product. For safety sake, please use equivalent GDT for replacement.

Storage

The packaged GDT should be placed in a dry, ventilted and non-corrosive environment.

Installation Position

Do not install the GDT in a touchable position.

Mechanical Stress

Do not take violent action such as knocking when assembling, to avoid product failure.